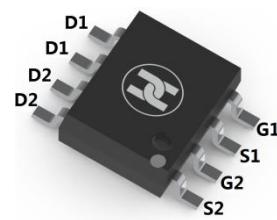


Dual N-Channel Enhancement Mode Field Effect Transistor

FEATURES

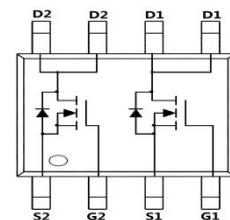
- V_{DS} (V) = 60V
- I_D = 6.3A (V_{GS} = 10V)
- $R_{DS(ON)} < 25m\Omega$ (V_{GS} = 10V)
- $R_{DS(ON)} < 30m\Omega$ (V_{GS} = 4.5V)



MECHANICAL DATA

- Case: SOP-8
- Case Material: Molded Plastic. UL flammability
- Classification Rating: 94V-0
- Weight: 0.3 grams (approximate)

SOP-8



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

| Parameter | Symbol | Maximum | Units |
|--|----------------|------------|-------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current ^A | I_D | 6.3 | A |
| $T_A=70^\circ C$ | | 5 | |
| Pulsed Drain Current ^B | I_{DM} | 40 | |
| Power Dissipation | P_D | 2 | W |
| $T_A=70^\circ C$ | | 1.28 | |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Units |
|--|-----------------|-----|------|-------|
| Maximum Junction-to-Ambient ^A | $R_{\theta JA}$ | 50 | 62.5 | °C/W |
| Maximum Junction-to-Ambient ^A | | 73 | 110 | °C/W |
| Maximum Junction-to-Lead ^C | $R_{\theta JL}$ | 31 | 40 | °C/W |

Dual N-Channel Enhancement Mode Field Effect Transistor

ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|-----------------------------|---------------------------------------|---|-----|----------|----------|------------------|
| STATIC PARAMETERS | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $I_D=250\mu\text{A}, V_{GS}=0\text{V}$ | 60 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=48\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$ | | | 1 5 | μA |
| I_{GSS} | Gate-Body leakage current | $V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$ | | | 100 | nA |
| $V_{GS(\text{th})}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=250\mu\text{A}$ | 1 | 2.1 | 3 | V |
| $I_{D(\text{ON})}$ | On state drain current | $V_{GS}=10\text{V}, V_{DS}=5\text{V}$ | 40 | | | A |
| $R_{DS(\text{ON})}$ | Static Drain-Source On-Resistance | $V_{GS}=10\text{V}, I_D=6.3\text{A}$ $T_J=125^\circ\text{C}$ | | 20 34 | 25 42 | $\text{m}\Omega$ |
| | | $V_{GS}=4.5\text{V}, I_D=5.7\text{A}$ | | 22 | 30 | $\text{m}\Omega$ |
| g_{FS} | Forward Transconductance | $V_{DS}=5\text{V}, I_D=6.3\text{A}$ | | 27 | | S |
| V_{SD} | Diode Forward Voltage | $I_S=1\text{A}, V_{GS}=0\text{V}$ | | 0.74 | 1 | V |
| I_S | Maximum Body-Diode Continuous Current | | | | 3 | A |
| DYNAMIC PARAMETERS | | | | | | |
| C_{iss} | Input Capacitance | $V_{GS}=0\text{V}, V_{DS}=30\text{V}, f=1\text{MHz}$ | | 1920 | 2300 | pF |
| C_{oss} | Output Capacitance | | | 155 | | pF |
| C_{rss} | Reverse Transfer Capacitance | | | 116 | | pF |
| R_g | Gate resistance | $V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$ | | 0.65 | 0.8 | Ω |
| SWITCHING PARAMETERS | | | | | | |
| $Q_g(10\text{V})$ | Total Gate Charge | $V_{GS}=10\text{V}, V_{DS}=30\text{V}, I_D=6.3\text{A}$ | | 47.6 | 58 | nC |
| $Q_g(4.5\text{V})$ | Total Gate Charge | | | 24.2 | 30 | nC |
| Q_{gs} | Gate Source Charge | | | 6 | | nC |
| Q_{gd} | Gate Drain Charge | | | 14.4 | | nC |
| $t_{D(\text{on})}$ | Turn-On Delay Time | $V_{GS}=10\text{V}, V_{DS}=30\text{V}, R_L=4.7\Omega, R_{\text{GEN}}=3\Omega$ | | 7.6 | | ns |
| t_r | Turn-On Rise Time | | | 5 | | ns |
| $t_{D(\text{off})}$ | Turn-Off Delay Time | | | 28.9 | | ns |
| t_f | Turn-Off Fall Time | | | 5.5 | | ns |
| t_{rr} | Body Diode Reverse Recovery Time | $I_F=6.3\text{A}, dI/dt=100\text{A}/\mu\text{s}$ | | 33.2 | 40 | ns |
| Q_{rr} | Body Diode Reverse Recovery Charge | $I_F=6.3\text{A}, dI/dt=100\text{A}/\mu\text{s}$ | | 43 | | nC |

A: The value of R_{0JA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The R_{0JA} is the sum of the thermal impedance from junction to lead R_{JL} and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

Dual N-Channel Enhancement Mode Field Effect Transistor

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

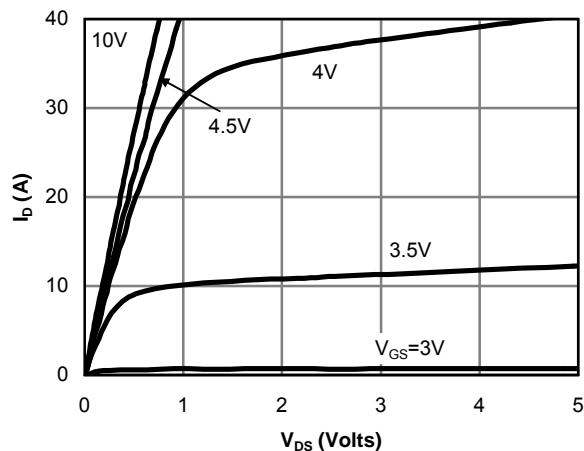


Fig 1: On-Region Characteristics

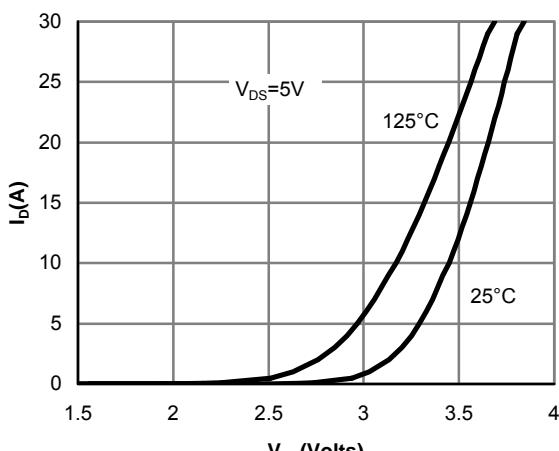


Figure 2: Transfer Characteristics

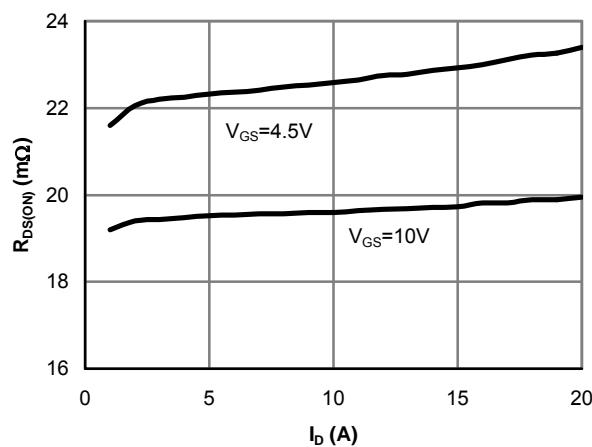


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

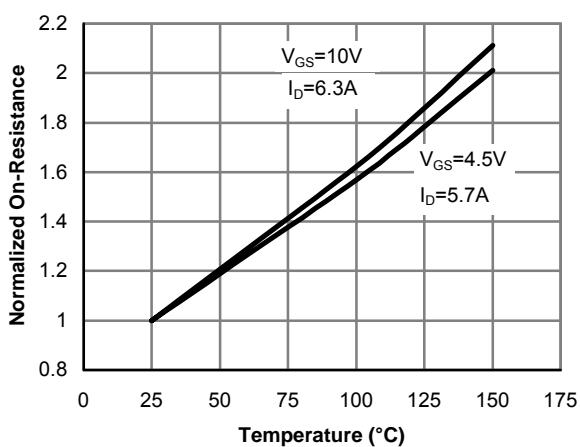


Figure 4: On-Resistance vs. Junction Temperature

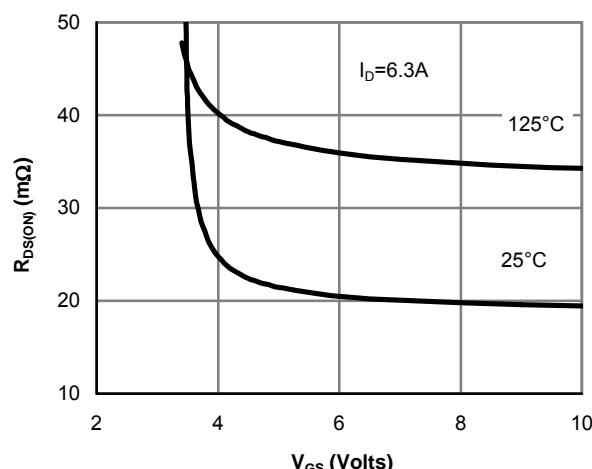


Figure 5: On-Resistance vs. Gate-Source Voltage

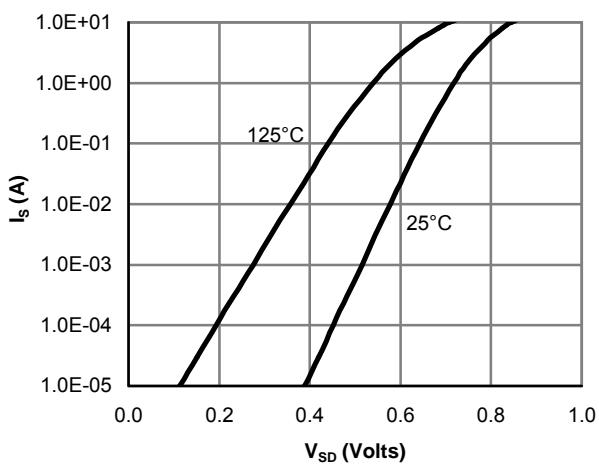


Figure 6: Body-Diode Characteristics

Dual N-Channel Enhancement Mode Field Effect Transistor

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

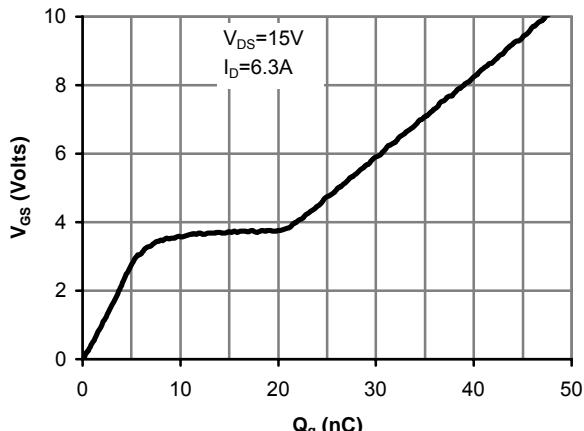


Figure 7: Gate-Charge Characteristics

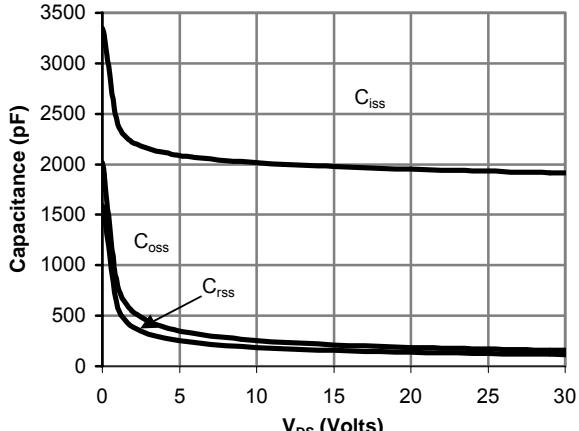


Figure 8: Capacitance Characteristics

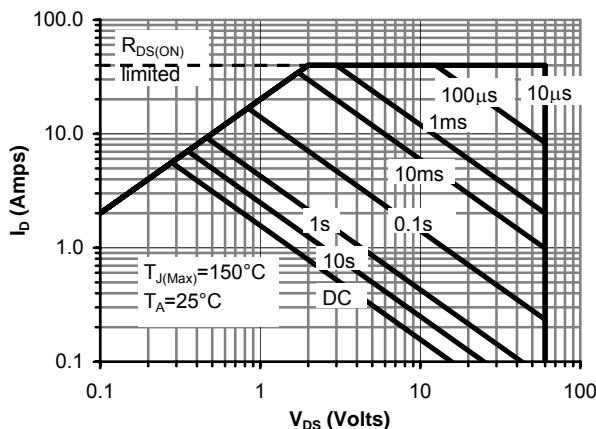


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

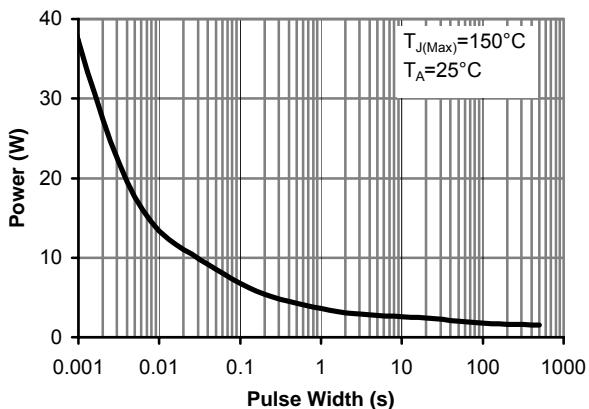


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

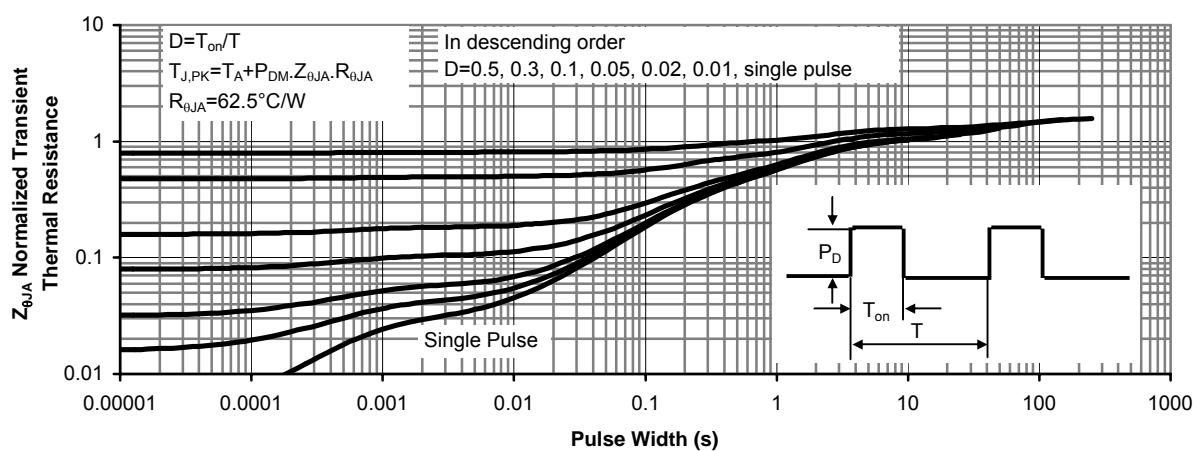
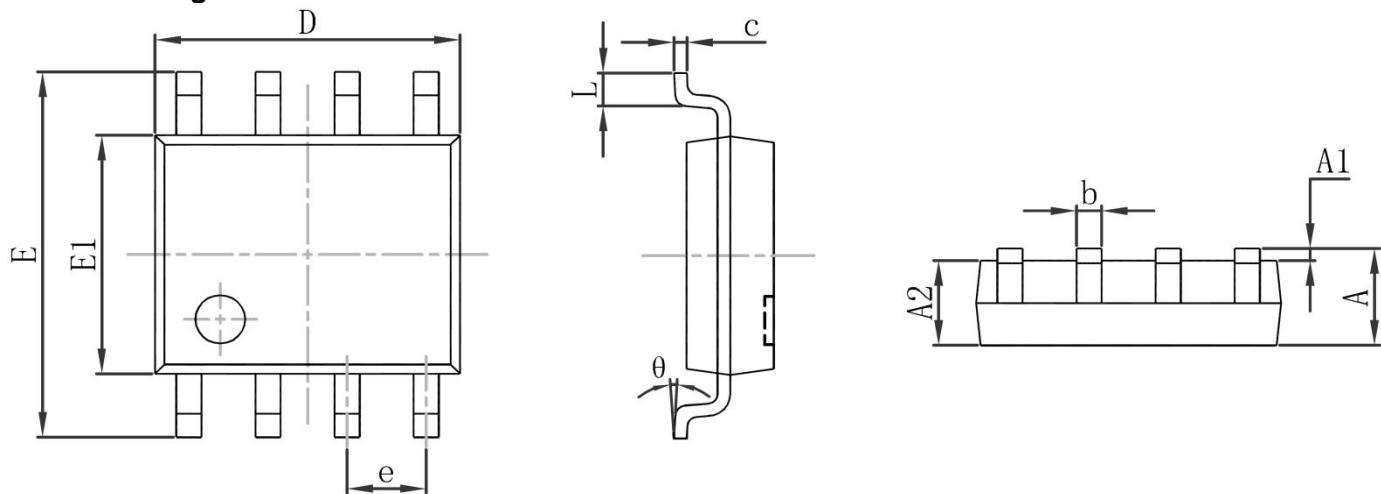


Figure 11: Normalized Maximum Transient Thermal Impedance

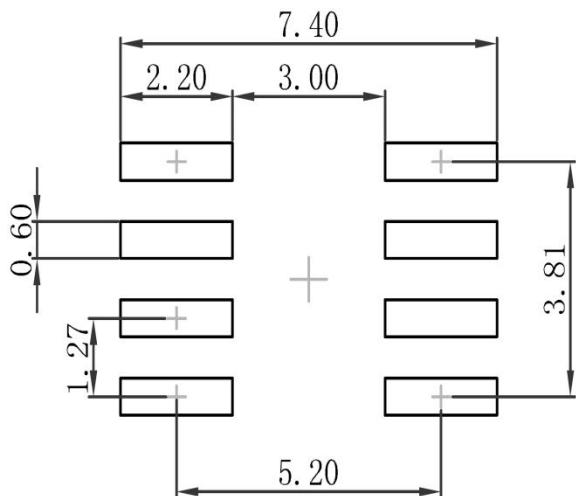
Dual N-Channel Enhancement Mode Field Effect Transistor

SOP-8 Package Outline Dimensions



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 |
| b | 0.330 | 0.510 | 0.013 | 0.020 |
| c | 0.170 | 0.250 | 0.007 | 0.010 |
| D | 4.800 | 5.000 | 0.189 | 0.197 |
| e | 1.270(BSC) | | 0.050 (BSC) | |
| E | 5.800 | 6.200 | 0.228 | 0.244 |
| E1 | 3.800 | 4.000 | 0.150 | 0.157 |
| L | 0.400 | 1.270 | 0.016 | 0.050 |
| θ | 0° | 8° | 0° | 8° |

SOP-8 Suggested Pad Layout



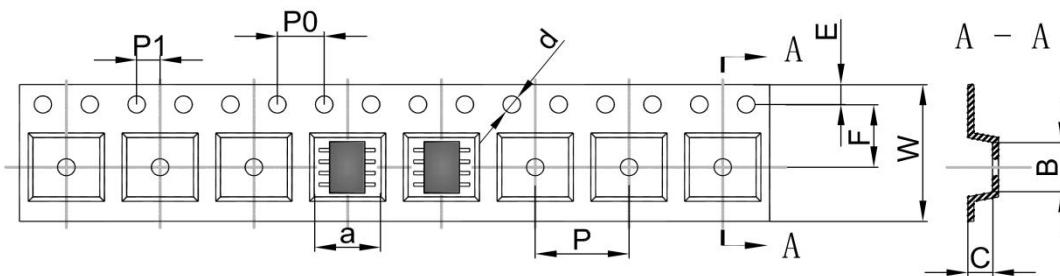
Note:

1. Controlling dimension: in millimeters
2. General tolerance: ±0.05mm
3. The pad layout is for reference purposes only

Dual N-Channel Enhancement Mode Field Effect Transistor

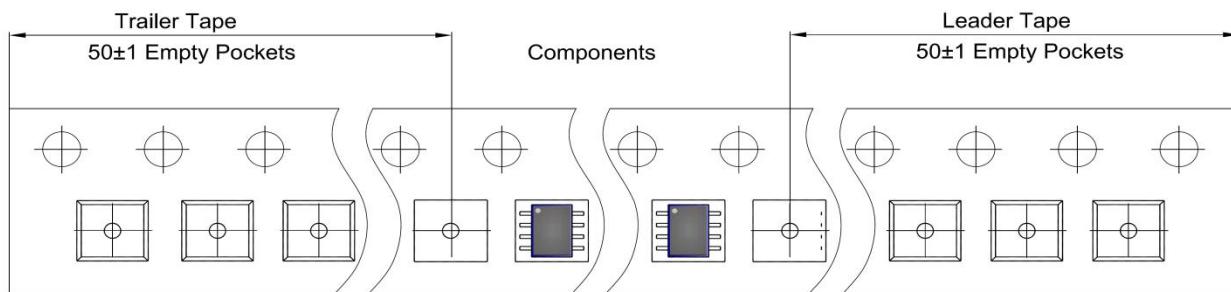
SOP-8 Tape and Reel

SOP-8 Embossed Carrier Tape

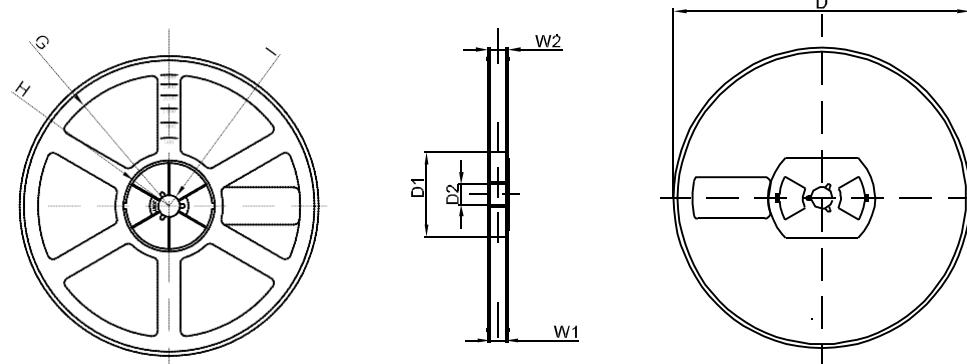


| TYPE | DIMENSIONS ARE IN MILLIMETER | | | | | | | | | |
|-----------|------------------------------|------|------|-------|------|------|------|------|------|-------|
| | A | B | C | d | E | F | P0 | P | P1 | W |
| SOP-8 | 6.40 | 5.40 | 2.10 | Ø1.50 | 1.75 | 5.50 | 4.00 | 8.00 | 2.00 | 12.00 |
| TOLERANCE | ±0.1 | ±0.1 | ±0.1 | ±0.1 | ±0.1 | ±0.1 | ±0.1 | ±0.1 | ±0.1 | ±0.1 |

SOP-8 Tape Leader and Trailer



SOP-8 Reel



| REEL OPTION | DIMENSIONS ARE IN MILLIMETER | | | | | | | |
|-------------|------------------------------|--------|-------|---------|--------|-------|-------|-------|
| | D | D1 | D2 | G | H | I | W1 | W2 |
| 13" DIA | Ø330.00 | 100.00 | 13.00 | R151.00 | R56.00 | R6.50 | 12.40 | 17.60 |
| TOLERANCE | ±2 | ±1 | ±1 | ±1 | ±1 | ±1 | ±1 | ±1 |